

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **OZAKI**, Takashi, et al.

Attention: Applications Division

Serial Number: 10/528,137

Group Art Unit: 1763

Filed: December 12, 2005

P.T.O. Confirmation No.: 2307

For:

SUBSTRATE PROCESSING APPARATUS AND METHOD FOR

MANUFACTURING A SEMICONDUCTOR DEVICE

REQUEST FOR CORRECTED FILING RECEIPT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Date: April 18, 2006

Sir:

Please supply the undersigned attorney with a corrected filing receipt for the aboveidentified application. The undersigned also respectfully requests that the Patent and Trademark Office records be amended to reflect the correction.

In reviewing the official Filing Receipt, we noted an error in that the title is incorrect and should read as --SUBSTRATE PROCESSING APPARATUS AND METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE--. A copy of the Declaration is enclosed which indicates the correct information. We are enclosing a copy of the filing receipt with the corrections highlighted.

In the event that any fees are required in connection with this paper, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, KRATZ, QUINTOS, HANSON & BROOKS, LLP

William L. Brooks Attorney for Applicants Reg. No. 34,129

WLB/bjb Atty. Docket No. **050161** Suite 1000 1725 K Street, N.W. Washington, D.C. 20006 (202) 659-2930

23850

PATENT TRADEMARK OFFICE

Enclosures: Official Filing Receipt and Declaration



United States Patent and Trademark Office

TED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Viginia 22313-1450 www.uspto.gov

APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/528 137	12/12/2005	1763	1630	050161	9	20	6

CONFIRMATION NO. 2307

23850 1725 K STREET, NW

SUITE 1000 WASHINGTON, DC 20006

ARMSTRONG, KRATZ, QUINTOS, HANSON& BROOKS, 且 F HANSON & BROOKS, LLP

FILING RECEIPT *OC000000018141588*

Date Mailed: 02/28/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Power of Attorney: The patent practitioners associated with Customer Number 23850.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP04/01996 02/20/2004

Foreign Applications

JAPAN 2003-44049 02/21/2003 JAPAN 2003-44904 02/21/2003 JAPAN 2003-87966 03/27/2003 JAPAN 2003-87884 03/27/2003

Projected Publication Date: 06/08/2006

Non-Publication Request: No

Early Publication Request: No

Title Substrate Processing apparatus and method for manufacturing q

- Gemi Conductor device -
Substrate-processing apparatus and method of producing a semiconductor device

Preliminary Class

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PROTECTING YOUR INVENTION OUTSIDE THE UNITED STATES

Since the rights granted by a U.S. patent extend only throughout the territory of the United States and have no effect in a foreign country, an inventor who wishes patent protection in another country must apply for a patent in a specific country or in regional patent offices. Applicants may wish to consider the filing of an international application under the Patent Cooperation Treaty (PCT). An international (PCT) application generally has the same effect as a regular national patent application in each PCT-member country. The PCT process **simplifies** the filing of patent applications on the same invention in member countries, but **does not result** in a grant of "an international patent" and does not eliminate the need of applicants to file additional documents and fees in countries where patent protection is desired.

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Applicants also are advised that in the case of inventions made in the United States, the Director of the USPTO must issue a license before applicants can apply for a patent in a foreign country. The filing of a U.S. patent application serves as a request for a foreign filing license. The application's filing receipt contains further information and guidance as to the status of applicant's license for foreign filing.

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For information on preventing theft of your intellectual property (patents, trademarks and copyrights), you may wish to consult the U.S. Government website, http://www.stopfakes.gov. Part of a Department of Commerce initiative, this website includes self-help "toolkits" giving innovators guidance on how to protect intellectual property in specific countries such as China, Korea and Mexico. For questions regarding patent enforcement issues, applicants may call the U.S. Government hotline at 1-866-999-HALT (1-866-999-4158).

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DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

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	ation of which is attached hereto u					
☐ was file	d ona	s United States Application	on Number or PCT Internation	onal		
Applicat	ion Number	and was a	mended on (if applic	able).		
I hereby stat claim(s), as	te that I have reviewed and unders amended by any amendment refer	tand the contents of the a	bove-identified specification	, including the		
I acknowled Regulations	ge the duty to disclose information, § 1.56.	n which is material to pat	entability as defined in Title	37, Code of Federal		
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applications. Se	2003-44049	Japan	21/2/2003	☑ Yes ☐ No		
note rty	(Number)	(Country)	(Day/Month/Year Filed)	⊠ I⇔ □ N0		
	2003-44904	Japan	31/2/2003	8 6		
	(Number)	(Country)	21/2/2003 (Day/Month/Year Filed)	⊠ Yes □ No		
	2003-87966	Japan	27/3/2003			
	(Number)	(Country)	(Day/Month/Year Filed)	☑ Yes ☐ No		
	2003-87884	Japan		5		
	(Number)	(Country)	27/3/2003 (Day/Month/Year Filed)	🛛 Yes 🗌 No		
(See note B)	See attached list for	st for additional prior foreign applications				
in the manner	on the benefit under Title 35, United subject matter of each of the claim or provided by the first paragraph of which is material to patentability a ween the filing date of the prior	of Title 35, United States as defined in Title 37. Co	of disclosed in the prior Uni Code, § 112, I acknowledge	ted States application the duty to disclose		
List prior U.S. Applications)		Status				
тррпсановзу	(Application Serial No.)	(Filing Date) Patented Pendir		ng 🔲 Abandoned		
	(Application Serial No.)	(Filing Date)	Patented Pendi	ng Abandoned		
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